

## TO-220AB Plastic-Encapsulate MOSFETS

### IRF630B N-Channel Power MOSFET

#### GENERAL DESCRIPTION

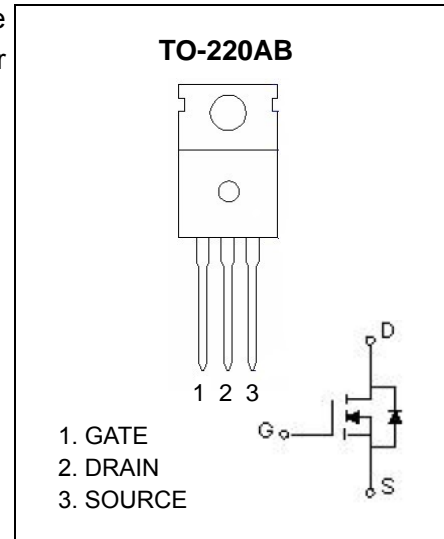
It uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge .This device is suitable for high current load applications.

#### FEATURE

- High current rating
- Ultra lower  $R_{DS(on)}$
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

#### APPLICATION

- Power switching application
- Load switching in high circuit application
- DC/DC converters



#### Maximum ratings ( $T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	200	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	9	A
Pulsed Drain Current	$I_{DM}$	37	
Single Pulsed Avalanche Energy (note1)	$E_{AS}$	250	mJ
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	62.5	$^{\circ}\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^{\circ}\text{C}$
Storage Temperature Range	$T_{STG}$	-55 ~+150	
Maximum lead temperature for soldering purposes , 1/8"from case for 5 seconds	$T_L$	260	

**Electrical characteristics (T<sub>a</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Off characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	200			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =200V, V <sub>GS</sub> =0V			25	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
<b>On characteristics (note2)</b>						
Gate-threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2		4	V
Static drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.4A			400	mΩ
Forward transconductance	g <sub>fs</sub>	V <sub>DS</sub> =50V, I <sub>D</sub> =5.4A	3.8			S
<b>Dynamic characteristics (note 3)</b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f =1MHz		800		pF
Output capacitance	C <sub>oss</sub>			240		
Reverse transfer capacitance	C <sub>rss</sub>			76		
<b>Switching characteristics (note 3)</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> =100V, V <sub>GS</sub> =10V, R <sub>G</sub> =12Ω, I <sub>D</sub> =5.9A		9.4		ns
Turn-on rise time	t <sub>r</sub>			28		
Turn-off delay time	t <sub>d(off)</sub>			39		
Turn-off fall time	t <sub>f</sub>			20		
<b>Drain-Source Diode Characteristics</b>						
Drain-source diode forward voltage(note2)	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> =9A			2	V
Continuous drain-source diode forward current(note4)	I <sub>S</sub>				9.3	A
Pulsed drain-source diode forward current	I <sub>SM</sub>				37	A

**动态特性 Dynamic Characteristics**

输入电容 Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	550	720	pF
输出电容 Output capacitance	C <sub>oss</sub>		-	85	110	pF
反向传输电容 Reverse transfer capacitance	C <sub>rss</sub>		-	22	29	pF

**Notes :**

1. L=4.6mH, I<sub>L</sub>=9.9A, V<sub>DD</sub>=50V, R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C.
2. Pulse Test : Pulse width≤300μs, duty cycle ≤2%.
3. Guaranteed by design, not subject to production
4. Surface mounted on FR4 board, t≤10s